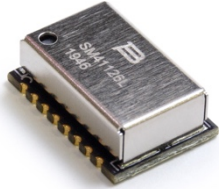


MATERIAL DECLARATION SHEET



Material Number	SM41126EL			
Product Line	LAN Transformer Module			
Compliance Date	2019/05/20			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
PCB								
1-1	Cuprous clad laminate	CCL	0.167299	Copper	7440-50-8	53	11.29536	21.31
				Glass fiber	65997-17-3	40	8.5248	
				Epoxy Resin	61788-97-4	7	1.49184	
1-2	Marking-Black Ink	Photoimageable solder mask	0.006448	Phenolic resin	9003-36-5	51.8	0.42476	0.82
				Barium sulfate	7727-43-7	31.1	0.25502	
				Carbon black	1333-86-4	10.4	0.08528	
				Silicon dioxide	14464-46-1	5.2	0.04264	
				Dimethylsilicone	63148-62-9	1.5	0.0123	
1-3	Marking-White Ink	Thermal curable marking ink	0.000349	Epoxy cresol novolac resin	29690-82-2	22	0.0088	0.04
				Epoxy resin	25068-38-6	22	0.0088	
				Silicon dioxide	14464-46-1	11	0.0044	
				Titanium dioxide	13463-67-7	33	0.0132	
				Cyanoguanidine	461-58-5	6	0.0024	
				Dimethylsilicone	63148-62-9	6	0.0024	
1-4	Plating-Ni	Ni coating PCB	0.000122	Nickel	7440-02-0	100	0.01554	0.02
1-5	Plating-Au	Au coating PCB	0.000052	Gold	7440-57-5	100	0.00666	0.01

MATERIAL DECLARATION SHEET



Common Mode Choke Coil x 2

2-1	Ferrite body	Ferrite Ni-Zn Series	0.015111	Iron oxide	1309-37-1	62.000	1.194	1.93
				Nickel oxide	1313-99-1	11.000	0.212	
				Zinc oxide	1314-13-2	20.000	0.385	
				Copper oxide	1317-38-0	7.000	0.135	
2-2	Copper/ Coating	Copper Wire	0.002355	Copper	7440-50-8	100.000	0.300	0.38
		Copper Colored Coating On The Magnet Wire_SFHW	0.000589	Polyurethane Resin	26680-22-8	100.000	0.075	
2-3	Terminal	Silver paste_DP4303W	0.000589	Silver	7440-22-4	100.000	0.075	0.08
2-4	Solder Base	S Nickel Pellets	0.000196	Nickel	7440-02-0	100.000	0.025	0.03
2-5	Solder	Lead Free Solder	0.000196	Tin	7440-31-5	100.000	0.025	0.03
2-6	Adhesive	EPOXY_ME-5890LC	0.000589	Epoxy resin	61788-97-4	50.000	0.038	0.08
				Carbon black	1333-86-4	46.000	0.035	
				Acrylated Aliphatic Urethane	68987-79-1	4.000	0.003	
SMD Pulse Transformer x 2								
3-1	Ferrite body	Ferrite Ni-Zn Series	0.214446	Iron oxide	1309-37-1	62.000	16.937	27.32
				Nickel oxide	1313-99-1	11.000	3.005	
				Zinc oxide	1314-13-2	20.000	5.464	
				Copper oxide	1317-38-0	7.000	1.912	
3-2	Copper/ Coating	Copper Wire	0.032782	Copper	7440-50-8	100.000	4.176	5.22
		Copper Colored Coating On The Magnet Wire_SFHW	0.008195	Polyurethane Resin	26680-22-8	100.000	1.044	
3-3	Terminal	Silver paste_DP4303W	0.006830	Silver	7440-22-4	100.000	0.870	0.87
3-4	Solder Base	S Nickel Pellets	0.001366	Nickel	7440-02-0	100.000	0.174	0.17

MATERIAL DECLARATION SHEET



3-5	Solder	Lead Free Solder	0.001366	Tin	7440-31-5	100.000	0.174	0.17
3-6	Adhesive	EPOXY_ME-5890LC	0.008195	Epoxy resin	61788-97-4	50.000	0.522	1.04
				Carbon black	1333-86-4	46.000	0.480	
				Acrylated Aliphatic Urethane	68987-79-1	4.000	0.042	
Iron shell								
4	STAINLESS STEEL STRIP	STEEL STRIP	0.27161	Stainless steel	12597-68-1	94.900	32.835	34.6
	Plating-Ni	Nickel		Nickel	7440-02-0	5.100	1.765	
Solder Paste								
5	Solder	Lead Free Solder	0.046315	Tin	7440-31-5	98.500	5.812	5.90
				Silver	7440-22-4	1.000	0.059	
				Copper	7440-50-8	0.500	0.030	
Total weight			0.785					

This Document was updated on: 2019/05/20

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.